



09/943880

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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s): Michael B. Ball**Patent No.:** 6,784,023 B2**Issued:** August 31, 2004**For:** METHOD OF FABRICATION OF
STACKED SEMICONDUCTOR DEVICES**Attorney Docket No.:** 2269-2769.6US

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

March 23, 2007
Date

Signature

Leta M. Howard
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OFFICE MISTAKES (37 C.F.R. § 1.322)**

Attn.: Certificate of Corrections Branch
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It is noted that several errors appear in this patent of a typographical nature. These errors are due to mistakes in printing on the part of the U.S. Patent and Trademark Office, and occurred through no fault of the Applicant. A certificate of correction in the form attached hereto is requested.

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Name: James R. Duzan
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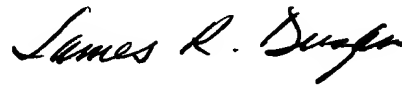
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Attached hereto in duplicate is Form PTO/SB/44 with at least one copy being suitable for printing.

Respectfully submitted,



James R. Duzan
Registration No. 28,393
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Date: March 23, 2007
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UNITED STATES PATENT AND TRADEMARK OFFICE
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INVENTOR(S) : Michael B. Ball

Page 1 of 1

It is certified that errors appear in the above-identified patent and that said Letters Patent are hereby corrected as shown below:

On the title page:

In ITEM (56) "References Cited"

after the last entry appearing in the "FOREIGN PATENT DOCUMENTS" section, insert:

-- OTHER PUBLICATIONS

IBM Technical Disclosure Bulletin, P.F. Iafrate, High
Density and Speed Performance Chip Joining
Procedure and Package, Vol. 15, No. 4, Pg. 1281.--

In the specification:

COLUMN 1, LINE 7,

change "pending," to --now U.S. Patent 6,337,227 issued
Jan. 8, 2002,--

MAILING ADDRESS OF SENDER:

PATENT NO. 6,784,023 B2

James R. Duzan
230 South 500 East, Suite 300
Salt Lake City, Utah 84102 USA

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